

10 9 8 7 6 5 4 3 2 1

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53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN: A0YAGI 2006/02/02 CHKD: YMAEDA 2006/02/03 APPR: NUKITA 2006/02/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY Y. A0YAGI	DATE 2006/01/30	TITLE 1.25 W-TO-B CONN. 51021,53261 MATING CROSS SECTION			
	10 OVER 30 UNDER	± ---	CHECKED BY Y. MAEDA	DATE 2006/01/30	MOLEX INCORPORATED			
	30 OVER	± ---	APPROVED BY N. UKITA	DATE 2006/01/30	DOCUMENT NO. SD-51021-002			
	ANGULAR	± --- °	MATERIAL NO. SEE CHART		SHEET NO. 1 OF 1			
0	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

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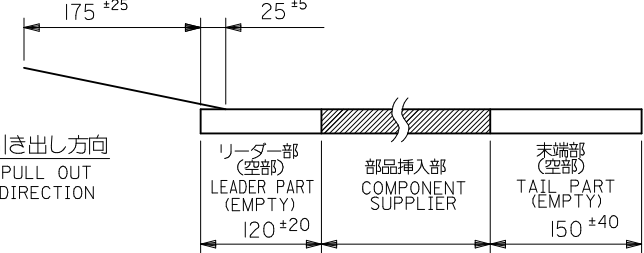
4

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注記  
NOTES

- 53261-\*\*-19 の詳細寸法については図面 SD-53261-024 を参照下さい。  
RE DETAILED DIMENSIONS, SEE SD-53261-024
- 梱包数量: 1000個/リール  
NUMBER OF CONNECTOR: 1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH  
トップテープリーダー部 TOP TAPE LEADER PART  
トップテープ未接着部 TOP TAPE NON-BONDED PART



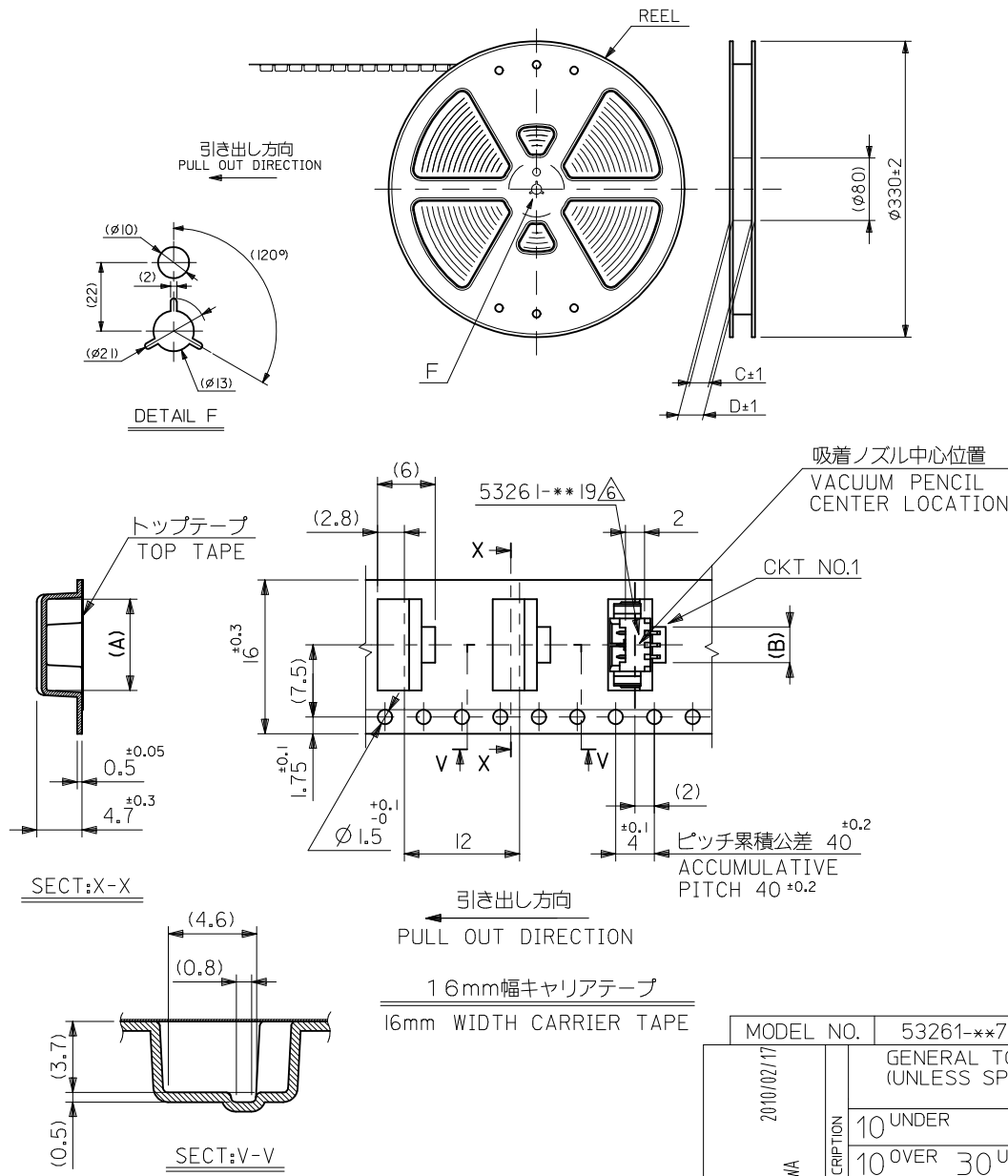
- 材料 (MATERIAL)  
キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)  
トップテープ (TOP TAPE): PET, PE, PEF  
リール (REEL): ポリスチレン (PS) <リサイクル材含む>  
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>

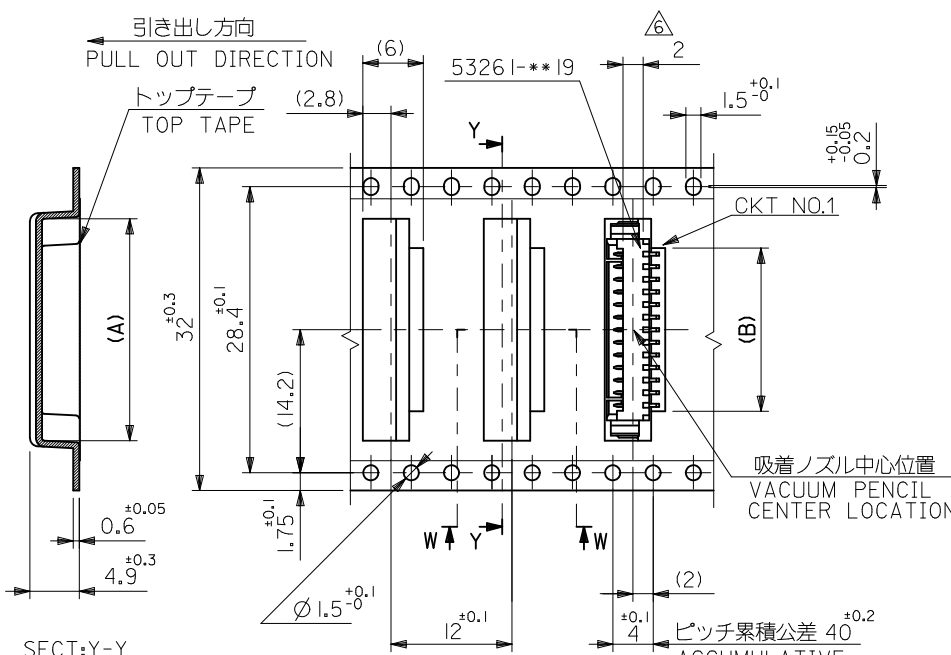
△ コネクタ、ハウジング平面部  
CONNECTOR, HOUSING FLAT AREA

- 本製品は 53261-\*\*-90 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53261-\*\*-90
- ELV及びRoHS適合品  
ELV AND RoHS COMPLIANT
- 本製品は乾燥剤入り、ハイバリア梱包仕様である。  
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

16	21.4	17.4	3.7	9.5	53261-0371	3				
			2.45	8.25	53261-0271	2				
キャリアテープ幅 CARRIER TAPE WIDTH					D	C	B	A	EMBOSSD TAPE PACKAGE オーダー番号 ORDER NO.	極数 CKT.

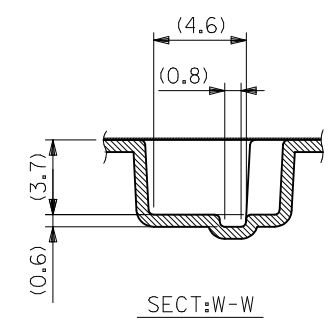
REVISED EC NO: D DRWN: YGOTO CHKD: KASAKAWA APPR:	MODEL NO.	53261-**-71		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	GENERAL TOLERANCES (UNLESS SPECIFIED)			DRAWN BY H. SHIMABUKUR		DATE '04/02/06		TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG		
	10 UNDER	±0.2		CHECKED BY K. TOJO		DATE '04/02/06				
	10 OVER 30 UNDER	±0.25		APPROVED BY NUKITA		DATE 2010/02/18		MOLEX INCORPORATED DOCUMENT NO. SD-53261-023 SHEET NO. 1 OF 3		
30 OVER	±0.3		MATERIAL NO. SEE TABLE & SHEET 2,3		SIZE A3					
ANGULAR ±3 °			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



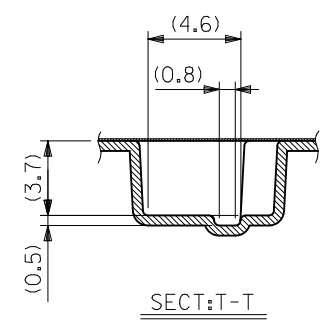


SECT:Y-Y

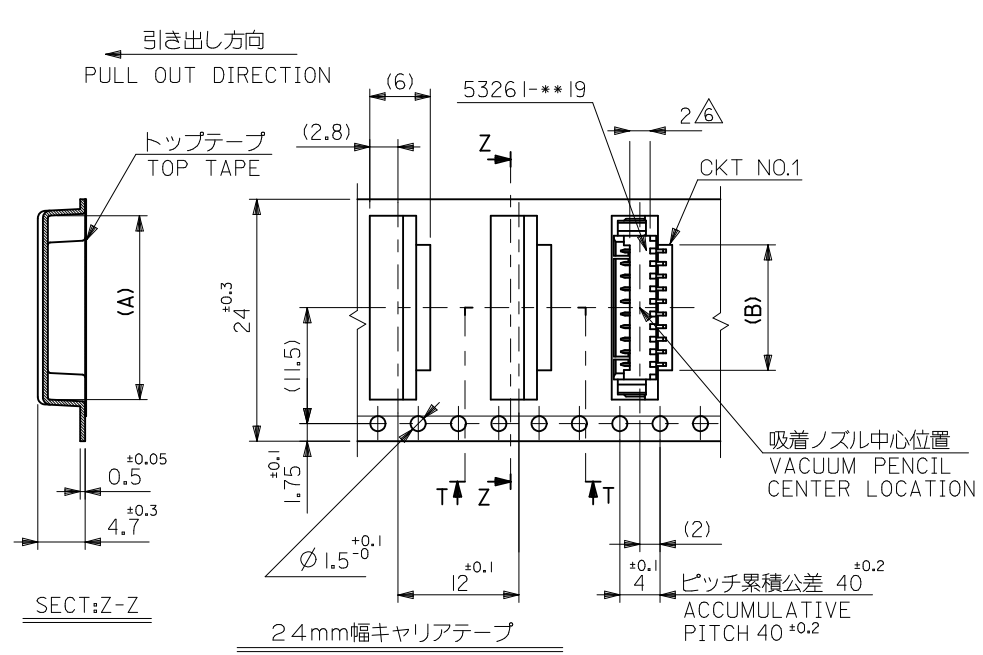
32mm幅キャリアテープ  
32mm WIDTH CARRIER TAPE



SECT:W-W



SECT:T-T



SECT:Z-Z

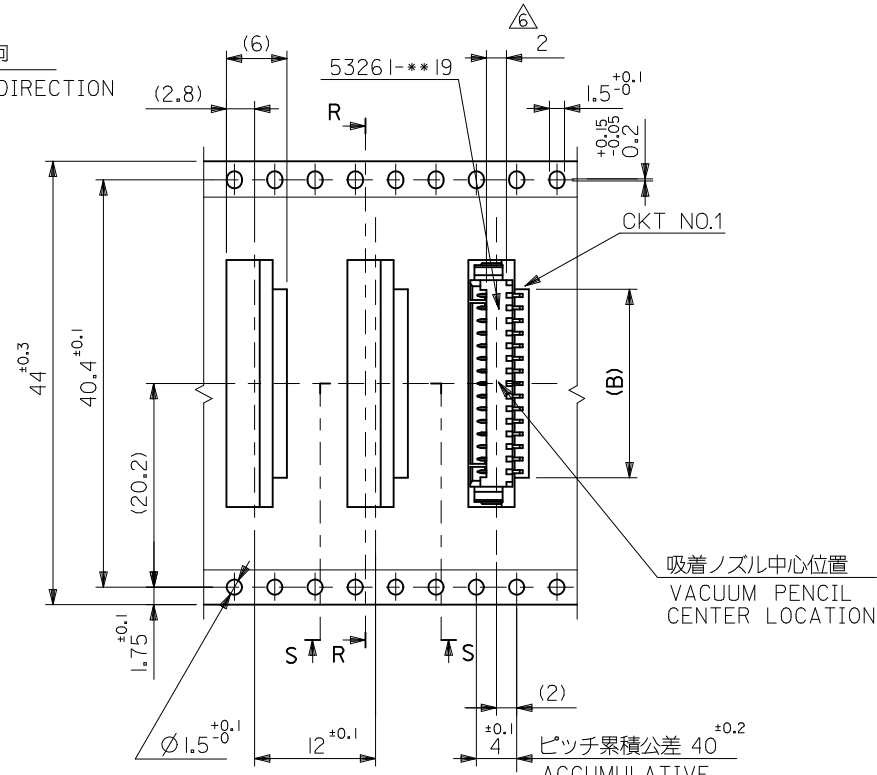
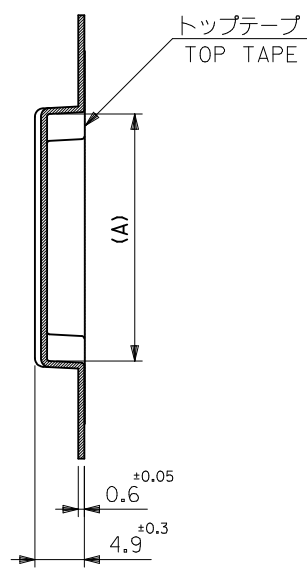
24mm幅キャリアテープ  
24mm WIDTH CARRIER TAPE

32	37.4	33.4	16.2	22	53261-1371	13
			14.95	20.75	-1271	12
24	29.4	25.4	13.7	19.5	-1171	11
			12.45	18.25	-1071	10
			11.2	17	-0971	9
			9.95	15.75	-0871	8
			8.7	14.5	-0771	7
			7.45	13.25	-0671	6
			6.2	12	-0571	5
			4.95	10.75	53261-0471	4

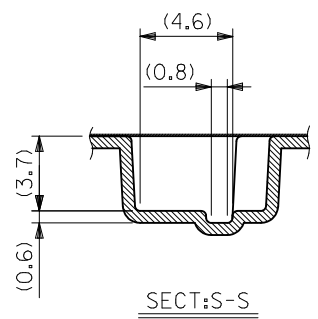
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	EMBOSSD TAPE PACKAGE	極数 CKT.
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MODEL NO.	53261-***71	DIMENSION STYLE	MM ONLY	SCALE	DESIGN UNITS	METRIC	THIRD ANGLE PROJECTION
REVISED	2010/02/17	GENERAL TOLERANCES (UNLESS SPECIFIED)	10 UNDER ±0.2	DRAWN BY	DATE	TITLE	1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG
EC NO.	D	10 OVER 30 UNDER ±0.25	H. SHIMABUKUR	'04/02/06			
DRWN:	YGOTO	30 OVER ±0.3	CHECKED BY	DATE			
CHKD:	KASAKAWA	ANGULAR ±3 °	APPROVED BY	DATE			
APPR:		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	NUKITA	2010/02/18			
REV		SIZE	A3	SEE TABLE & SHEET 1.3	MATERIAL NO.	DOCUMENT NO.	SHEET NO.

引き出し方向  
PULL OUT DIRECTION

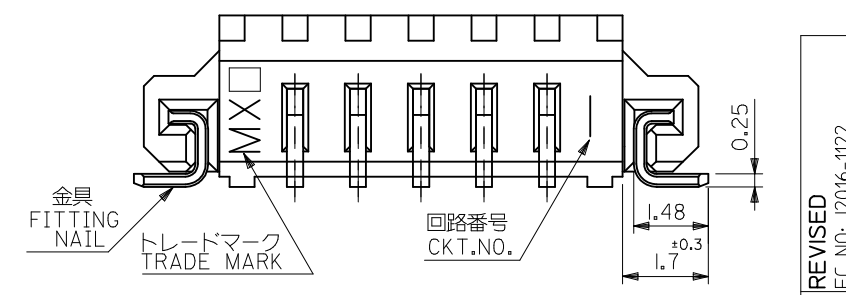
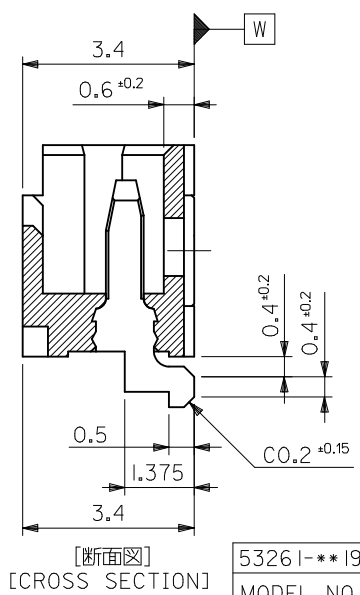
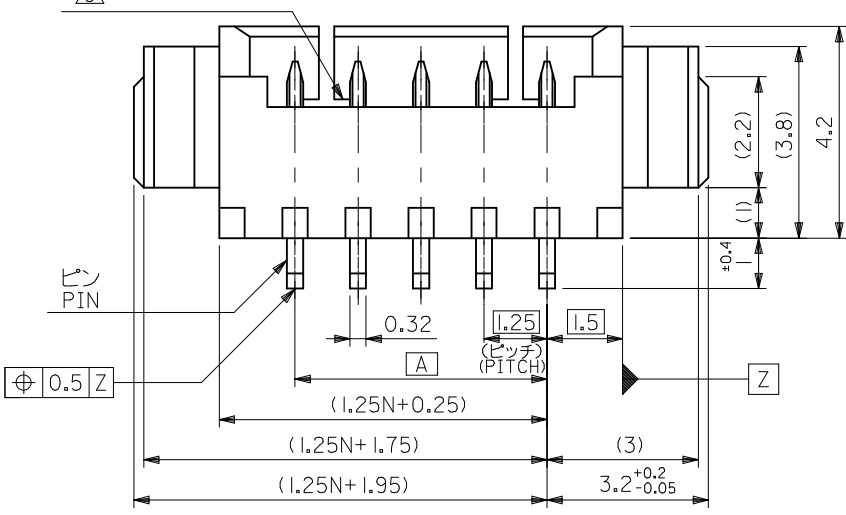
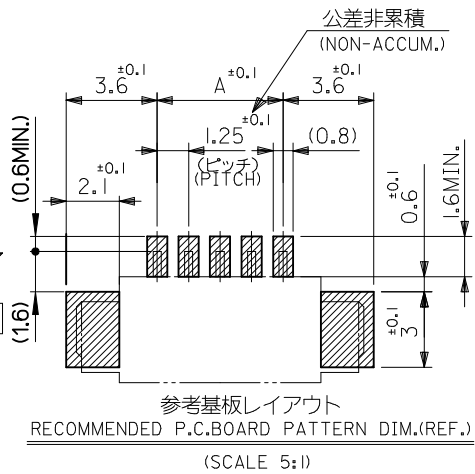
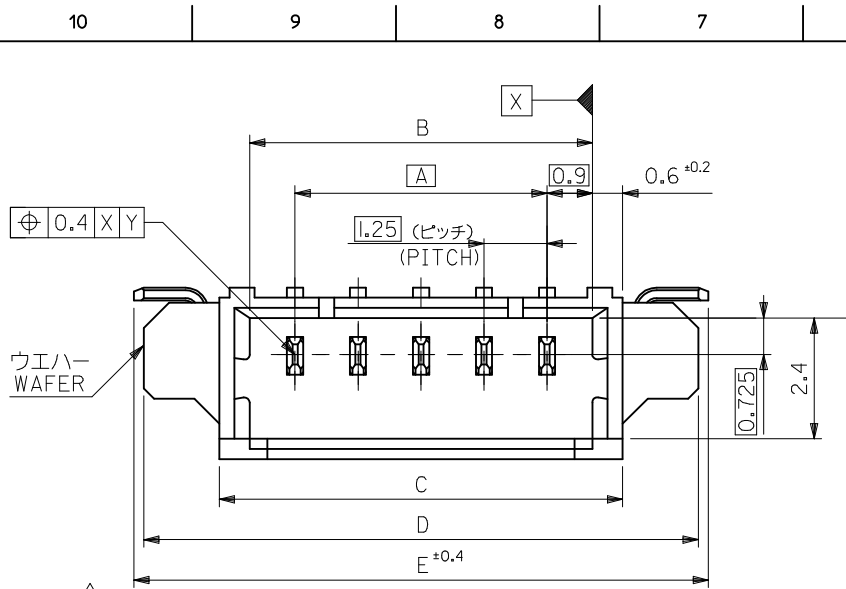


44mm幅キャリアテープ  
44mm WIDTH CARRIER TAPE



44	49.4	45.4	18.7	24.5	53261-1571	15
			17.45	23.25	53261-1471	14
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	EMBOSSD TAPE PACKAGE オーダー番号 ORDER NO.	極数 CKT.

REVISED	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
EC NO: D	2010/02/17	10 UNDER ±0.2	MM ONLY	---	METRIC	☉ □
DRWN: YGOTO		10 OVER 30 UNDER ±0.25	DRAWN BY DATE			TITLE
CHKD: KASAKAWA		30 OVER ±0.3	H. SHIMABUKUR '04/02/06			1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG
APPR:		ANGULAR ±3 °	CHECKED BY DATE			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	K. TOJO '04/02/06			
			APPROVED BY DATE			
			NUKITA 2010/02/18			
			MATERIAL NO.			
			SEE TABLE & SHEET 12			
			SIZE A3			
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
					MOLEX MOLEX INCORPORATED	
					DOCUMENT NO. SD-53261-023	SHEET NO. 3 OF 3



注記 NOTES

- 嵌合相手: 51021 シリーズ  
MATES WITH: 51021 SERIES
- 材質 MATERIAL  
ウエハー: NYLON46, UL94V-0  
ピン: リン青銅  
: PHOS-BRO  
: 銅メッキ 1.0 マイクロメートル以上  
: TIN 1.0 MICROMETER MINIMUM  
: ニッケル下地 1.0 マイクロメートル以上  
: NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM  
金具  
FITTING NAIL: リン青銅  
: PHOS-BRO  
: 銅メッキ 1.0 マイクロメートル以上  
: TIN 1.0 MICROMETER MINIMUM  
: ニッケル下地 1.0 マイクロメートル以上  
: NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM
- ロック窓は2, 3極は1箇所, 4極以上は2箇所とする。  
LOCKING WINDOW: ONE PLACE FOR 2 AND 3 CKT. AND TWO PLACES FOR MORE THAN 3 CKT.
- ソリダータール部のスレ量及び金具(補強板)のスレ量は基準面 W に対し、上方向 0.05MAX.、下方向に 0.1 MAX. とする。  
OFFSET BETWEEN BASIS PLANE W TO SOLDER TAIL BOTTOM AND FITTING NAIL BOTTOM:  
UPPER SIDE: 0.05MAX.  
LOWER SIDE: 0.1MAX.
- 本製品は 53261-\*\*-10 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53261-\*\*10
- ELV及びRoHS適合品  
ELV AND RoHS COMPLIANT.
- ソルダータール及び金具の平坦度は0.1以下。  
SOLDER TAIL & FITTING NAIL COPLANARITY TO BE 0.1 MAX.

26.4	26	23	21.8	20	53261-1771	53261-1719	17	
23.9	23.5	20.5	19.3	17.5	-1571	-1519	15	
22.65	22.25	19.25	18.05	16.25	-1471	-1419	14	
21.4	21	18	16.8	15	-1371	-1319	13	
20.15	19.75	16.75	15.55	13.75	-1271	-1219	12	
18.9	18.5	15.5	14.3	12.5	-1171	-1119	11	
17.65	17.25	14.25	13.05	11.25	-1071	-1019	10	
16.4	16	13	11.8	10	-0971	-0919	9	
15.15	14.75	11.75	10.55	8.75	-0871	-0819	8	
13.9	13.5	10.5	9.3	7.5	-0771	-0719	7	
12.65	12.25	9.25	8.05	6.25	-0671	-0619	6	
11.4	11	8	6.8	5	-0571	-0519	5	
10.15	9.75	6.75	5.55	3.75	-0471	-0419	4	
8.9	8.5	5.5	4.3	2.5	-0371	-0319	3	
53261-**-19	7.65	7.25	4.25	3.05	1.25	53261-0271	53261-0219	2
MODEL NO.	E	D	C	B	A	EMBOSSED TAPE PKG ORDER No.	MATERIAL NO.	極数 CKT.

REVISED EC NO: J2016-1122 DRWN: QHEJ1 CHKD: SAKIYAMA APPR: IKANEKO	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS		THIRD ANGLE PROJECTION	
	0.25 UNDER	UNDER	±0.03	MM ONLY		10:1	METRIC		
	0.25 OVER	0.5 UNDER	±0.05	DRAWN BY	DATE	TITLE			
	0.5 OVER	1.0 UNDER	±0.1	HS HIMABU	04/02/06	1.25 WIRE TO BOARD WAFER ASS FOR SMT			
1.0 OVER	10 UNDER	±0.2	CHECKED BY	DATE	molex				
10 OVER	30 UNDER	±0.25	KTOJO	04/02/06					
30 OVER		±0.3	APPROVED BY	DATE	DOCUMENT NO.		SHEET NO.		
ANGULAR	±3 °		MSASAO	04/02/06	SD-53261-024		1 OF 1		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
			A3						